

8E9011rs
(ON ENIMVARD) 台架圖

DESIGNATION

MM60-76***-***
 SERIES PREFIX
 No. OF CONTACTS
 SOCKET TYPE
 KEYING TYPE

CONTACT FINISH
 1: AU(0.1μm MIN.) OVER NI
 2: AU(0.3μm MIN.) OVER NI
 9: AU FLASH OVER NI
 MODIFY CODE
 0: 4.0mm HIGH WITH BOSS

版数 REV.	年月日 DATE	DON NO.	変更内容 DESCRIPTION	製図 DR.	担当 CHK.	査閲 APPD.	承認 APPD.

NOTE 1. PRODUCTION LOT No. AS INDICATED.
 (EX.) T901
 LOT NUMBER OF CURRENT MONTH
 MONTH (1 TO 9 FOR JAN. TO SEPT. RESPECTIVELY,
 OCT.:0, NOV.:X, DEC.:Y)
 YEAR (LAST DIGIT ONLY)
 MANUFACTURE CODE

NOTE 2. CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALIZATION.

NOTE 3. BEVEL MUST BE FREE OF CUTTING BURRS.

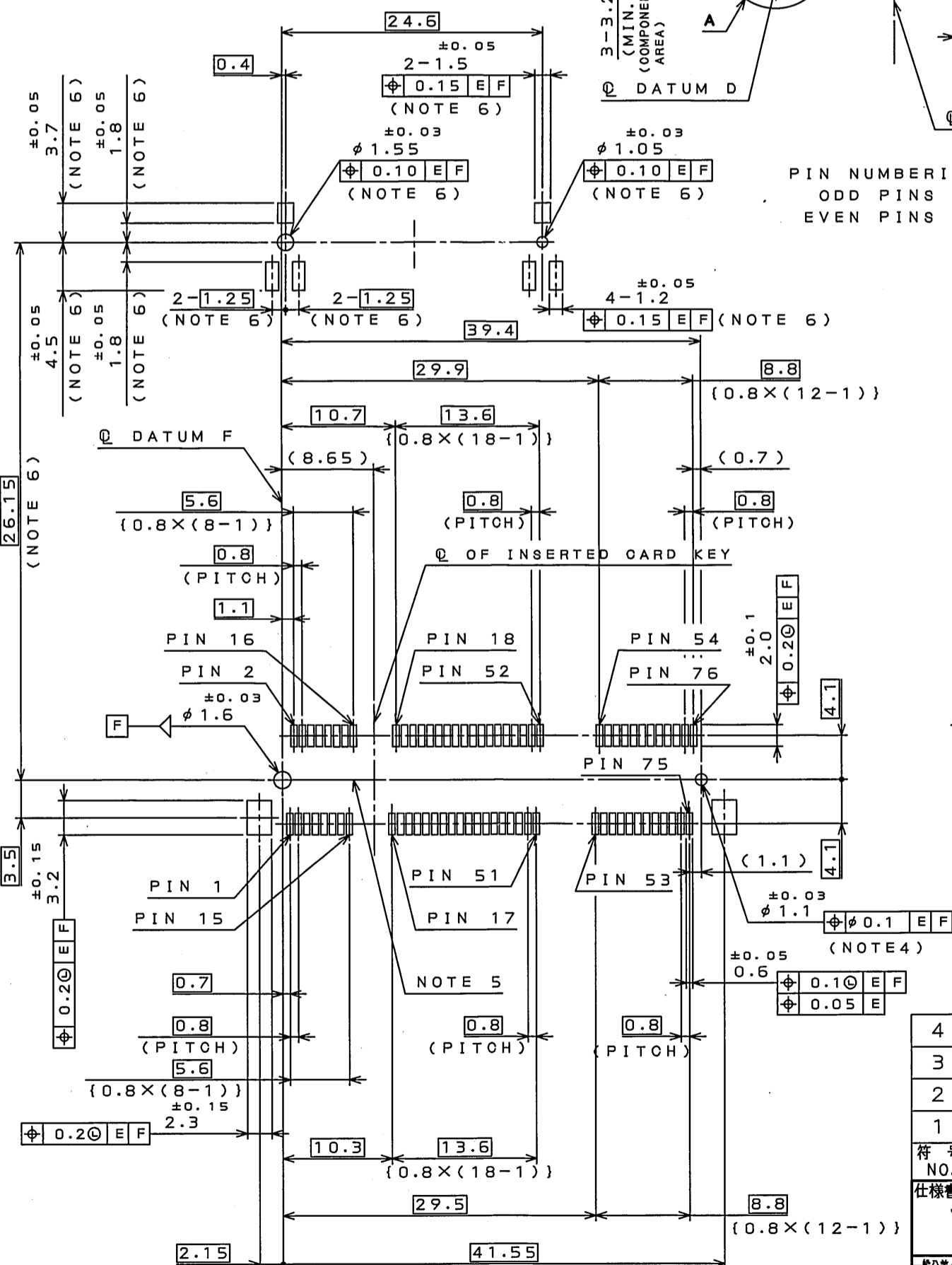
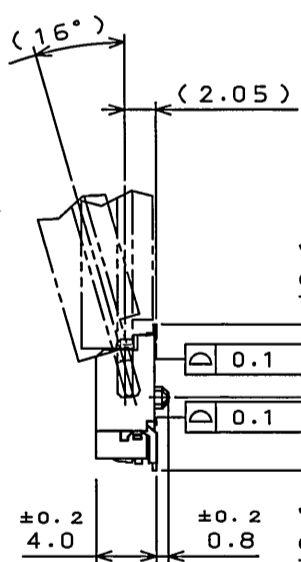
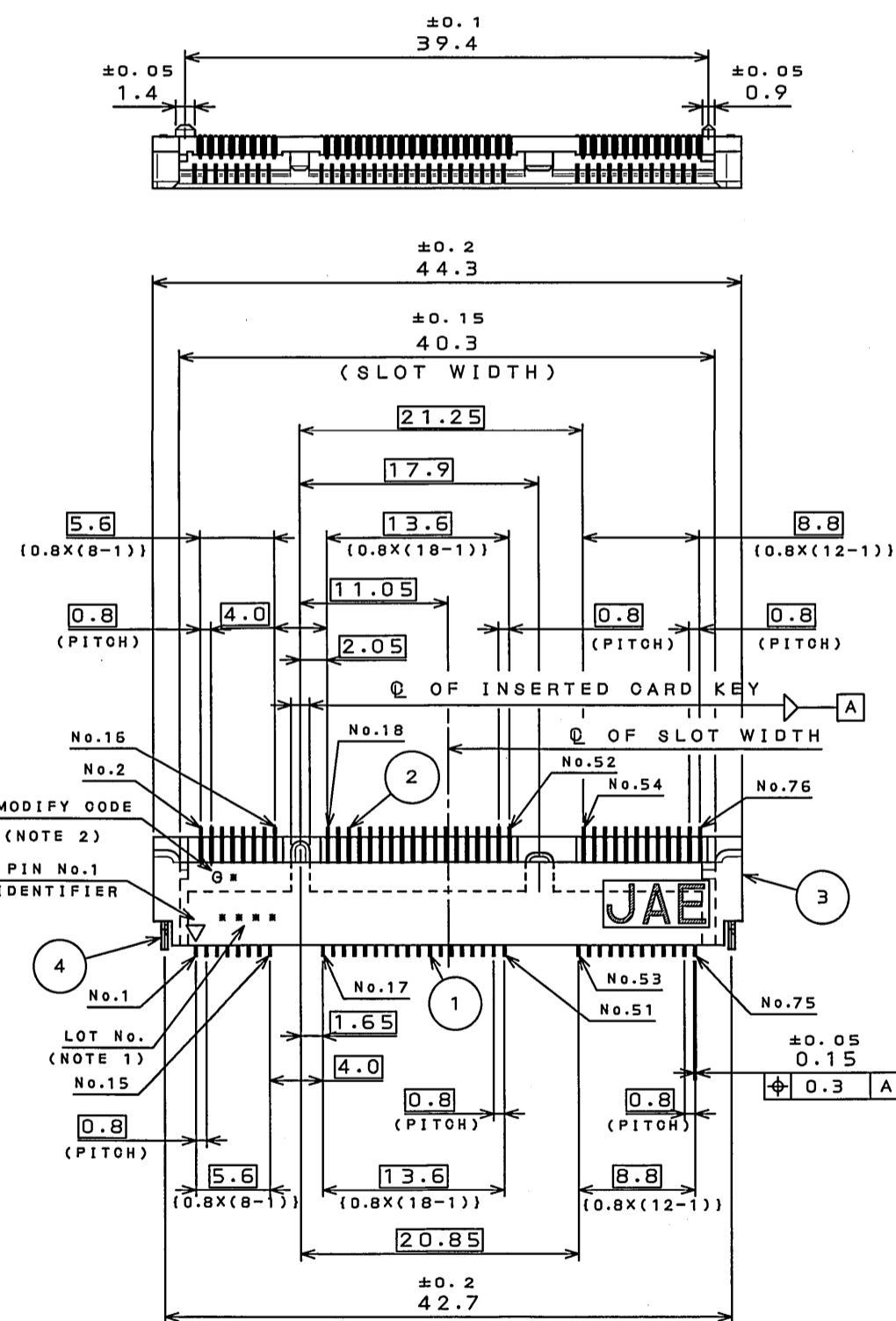
NOTE 4. THE HORIZONTAL AXIS FOR THE PATTERN IS ESTABLISHED BY A LINE THROUGH THE CENTER OF THE φ1.6 AND φ1.1 HOLES.
 THE VERTICAL AXIS IS 90° TO THE HORIZONTAL AXIS, THROUGH THE CENTER OF DATUM F.

NOTE 5. LOCATION OF INSERTED CARD EDGE IS ALIGNED WITH Q OF HOLES.

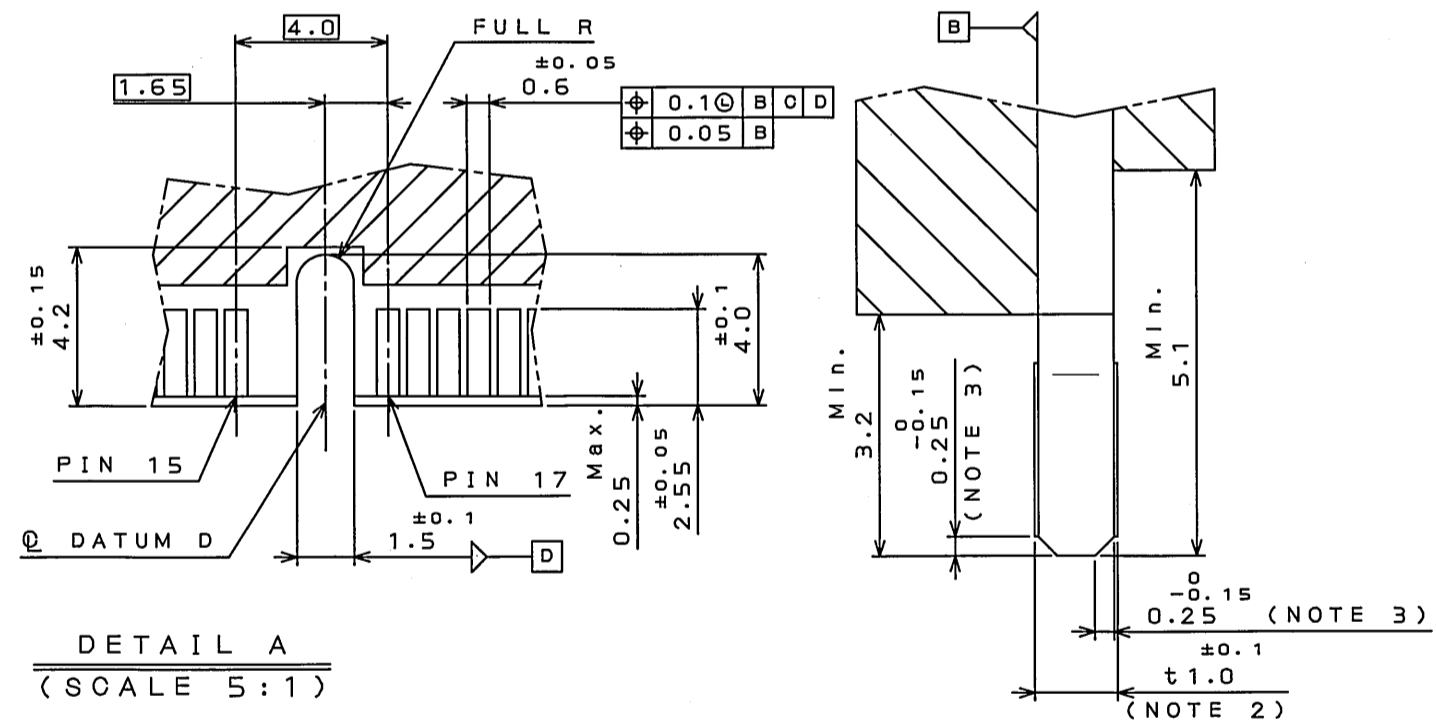
NOTE 6. ONLY WHEN THE LATCH SHOWN IN SJ105217(MM60-EZH039-B5) IS USED, THESE DIMENSIONS ARE APPLIED.

HATCHED AREAS ILLUSTRATE MAXIMUM AVAILABLE COMPONENT VOLUME.

APPLICABLE DISPLAY-MINI CARD(REF.)



PIN NUMBERING REFERENCE :
 ODD PINS - TOP SIDE
 EVEN PINS - BOTTOM SIDE



DETAIL A
(SCALE 5:1)

DETAIL B
(SCALE 10:1)

DATUM E IS THE TOP OF SURFACE OF PCB.

APPLICABLE P.C.B. DIMENSION(REF.)
 適合基板寸法(参考)

4 HOLD DOWN	2 COPPER ALLOY	TIN PLATING	
3 INSULATOR	1 THERMOPLASTIC		UL94 V-0
2 BOTTOM SIDE CONTACT	38 COPPER ALLOY	CONTACT AREA : REFER TO DESIGNATION SOLDERING AREA : GOLD FLASH OVER NI	
1 TOP SIDE CONTACT	38 COPPER ALLOY	CONTACT AREA : REFER TO DESIGNATION SOLDERING AREA : GOLD FLASH OVER NI	
符号 NO.	名称 DESCRIPTION	個数 QTY.	材料 MATERIAL
仕様書(SPECIFICATION)	第1版(ORIGINAL DATE)	尺度(SCALE)	シリーズ(SERIES)
JACS-10705	17.Jun.2010	2:1	MM60
製図 DR.	担当 CHK.	名称(TITLE)	
T.TSUJI		MM60-76B2-0*	
査閲 APPD.	承認 APPD.	質量(MASS)	備考 REMARKS
	M. Watanabe		日本航空電子工業株式会社 JAPAN AVIATION ELECTRONICS INDUSTRY, LTD.
			図面番号(DRAWING NO.) SJ110638
			版数 (REV.) 1